



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC139D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74LVC139DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74LVC139PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74LVC139BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1

### 4. Functional diagram

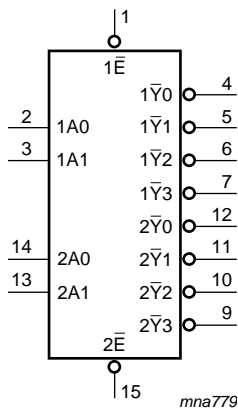
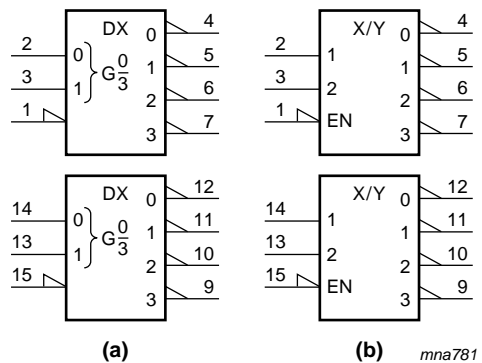


Fig 1. Logic symbol



- a) demultiplexer
- b) decoder

Fig 2. IEC logic symbol

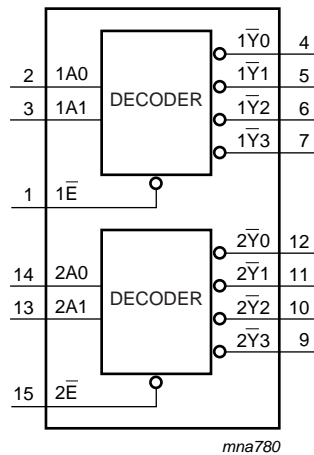


Fig 3. Functional diagram

## 5. Pinning information

### 5.1 Pinning

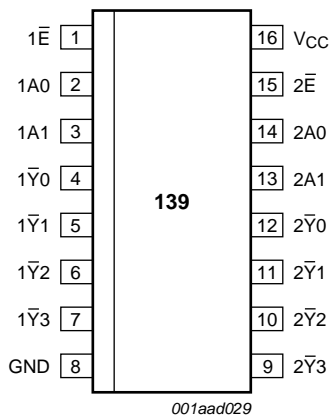
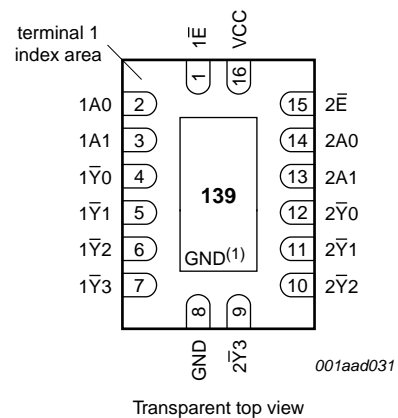


Fig 4. Pin configuration SO16 and (T)SSOP16



(1) The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig 5. Pin configuration DHVQFN14

### 5.2 Pin description

Table 2. Pin description

Name	Pin	Description
1E	1	enable input (active LOW)
2E	15	enable input (active LOW)
1A[0:1]	2, 3	address input
2A[0:1]	14, 13	address input
1Y[0:3]	4, 5, 6, 7	output

Table 2. Pin description ...continued

Name	Pin	Description
$2\bar{Y}[0:3]$	12, 11, 10, 9	output
GND	8	ground (0 V)
$V_{CC}$	16	positive supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input			Output			
nE	nA0	nA1	nY0	nY1	nY2	nY3
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	H	L	H	L	H	H
L	L	H	H	H	L	H
L	H	H	H	H	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$	-50	-	mA
$V_I$	input voltage		<sup>[1]</sup> -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
$V_O$	output voltage		<sup>[2]</sup> -0.5	$V_{CC} + 0.5$	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±50	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	<sup>[3]</sup> -	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO16 packages: above 70 °C derate linearly with 8 mW/K.

For SSOP16 and TSSOP16 packages: above 60 °C derate linearly with 5.5 mW/K.

For DHVQFN16 packages: above 60 °C derate linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature	in free air	-40		+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$	0	-	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0	-	10	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.2 \text{ V}$	1.08	-	-	1.08	-	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	-	-	1.7	-	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2.0	-	-	2.0	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.2 \text{ V}$	-	-	0.12	-	0.12	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	-	0.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$						
		$I_O = -100 \mu\text{A}; V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	$V_{CC} - 0.2$	-	-	$V_{CC} - 0.3$	-	V
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	-	1.05	-	V
		$I_O = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	-	1.65	-	V
		$I_O = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	-	-	2.05	-	V
		$I_O = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	-	2.25	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$						
		$I_O = 100 \mu\text{A}; V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	-	-	0.2	-	0.3	V
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.45	-	0.65	V
		$I_O = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.6	-	0.8	V
		$I_O = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	0.6	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.55	-	0.8	V
$I_I$	input leakage current	$V_{CC} = 3.6 \text{ V}; V_I = 5.5 \text{ V or GND}$	-	$\pm 0.1$	$\pm 5$	-	$\pm 20$	$\mu\text{A}$

**Table 6. Static characteristics ...continued**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$I_{CC}$	supply current	$V_{CC} = 3.6 \text{ V}$ ; $V_I = V_{CC}$ or GND; $I_O = 0 \text{ A}$	-	0.1	10	-	40	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per input pin ; $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ ; $V_I = V_{CC} - 0.6 \text{ V}$ ; $I_O = 0 \text{ A}$	-	5	500	-	5000	$\mu\text{A}$
$C_I$	input capacitance	$V_{CC} = 0 \text{ V to } 3.6 \text{ V}$ ; $V_I = \text{GND to } V_{CC}$	-	5.0	-	-	-	pF

[1] All typical values are measured at  $V_{CC} = 3.3 \text{ V}$  (unless stated otherwise) and  $T_{amb} = 25 \text{ }^\circ\text{C}$ .

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	nAn to $\bar{Y}_n$ ; see <a href="#">Figure 6</a> <sup>[2]</sup>						
		$V_{CC} = 1.2 \text{ V}$	-	14	-	-	-	ns
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.5	4.7	10.4	0.5	11.3	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.0	2.8	5.9	1.0	6.5	ns
		$V_{CC} = 2.7 \text{ V}$	1.0	3.0	6.3	1.0	8.0	ns
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	1.0	2.5	5.3	1.0	7.0	ns
		$n\bar{E}$ to $\bar{Y}_n$ ; see <a href="#">Figure 7</a> <sup>[2]</sup>						
		$V_{CC} = 1.2 \text{ V}$	-	14	-	-	-	ns
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	1.5	4.5	9.8	1.5	10.7	ns
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	2.1	2.7	5.6	2.1	6.1	ns
$V_{CC} = 2.7 \text{ V}$	1.0	2.8	5.4	1.0	7.0	ns		
$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	1.0	2.4	5.0	1.0	6.5	ns		
$t_{sk(o)}$	output skew time	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$ <sup>[3]</sup>	-	-	1.0	-	1.5	ns
$C_{PD}$	power dissipation capacitance	$V_I = \text{GND to } V_{CC}$ <sup>[4]</sup>						
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	5.6	-	-	-	pF
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	11.3	-	-	-	pF
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	16.4	-	-	-	pF

[1] Typical values are measured at  $T_{amb} = 25 \text{ }^\circ\text{C}$  and  $V_{CC} = 1.2 \text{ V}$ ,  $1.8 \text{ V}$ ,  $2.5 \text{ V}$ ,  $2.7 \text{ V}$ , and  $3.3 \text{ V}$  respectively.[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

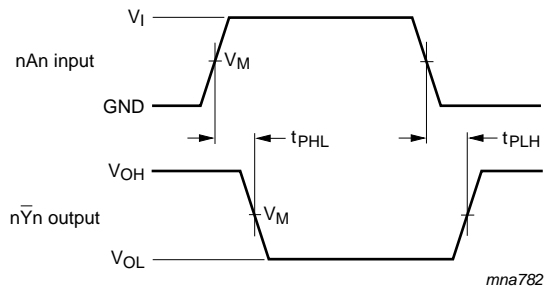
[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where: $f_i$  = input frequency in MHz;  $f_o$  = output frequency in MHz $C_L$  = output load capacitance in pF $V_{CC}$  = supply voltage in V

N = number of inputs switching,

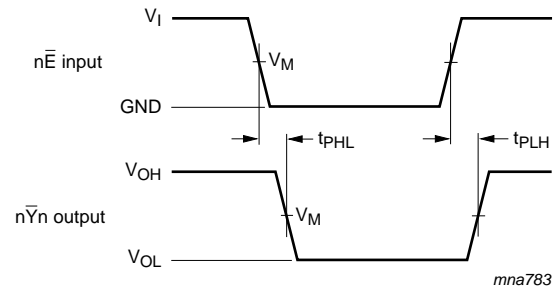
$$\Sigma(C_L \times V_{CC}^2 \times f_o) = \text{sum of outputs.}$$

## 11. Waveforms



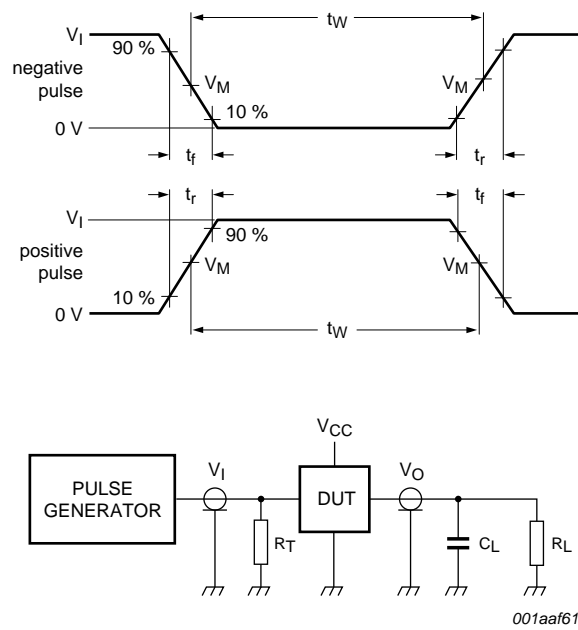
$V_M = 1.5 \text{ V}$  at  $V_{CC} \geq 2.7 \text{ V}$ .  
 $V_M = 0.5 \times V_{CC}$  at  $V_{CC} < 2.7 \text{ V}$ .  
 $V_{OL}$  and  $V_{OH}$  are the typical output voltage levels that occur with the output load.

**Fig 6. Input (nAn) to output (nYn) propagation delays**



$V_M = 1.5 \text{ V}$  at  $V_{CC} \geq 2.7 \text{ V}$ .  
 $V_M = 0.5 \times V_{CC}$  at  $V_{CC} < 2.7 \text{ V}$ .  
 $V_{OL}$  and  $V_{OH}$  are the typical output voltage levels that occur with the output load.

**Fig 7. Enable input (nE) to output (nYn) propagation delays**



001aa615

Test data is given in [Table 8](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

**Fig 8. Load circuitry for switching times**

**Table 8. Test data**

Supply voltage	Input		Load	
	$V_I$	$t_r, t_f$	$C_L$	$R_L$
1.2 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$
2.3 V to 2.7 V	$V_{CC}$	$\leq 2$ ns	30 pF	500 $\Omega$
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$



12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

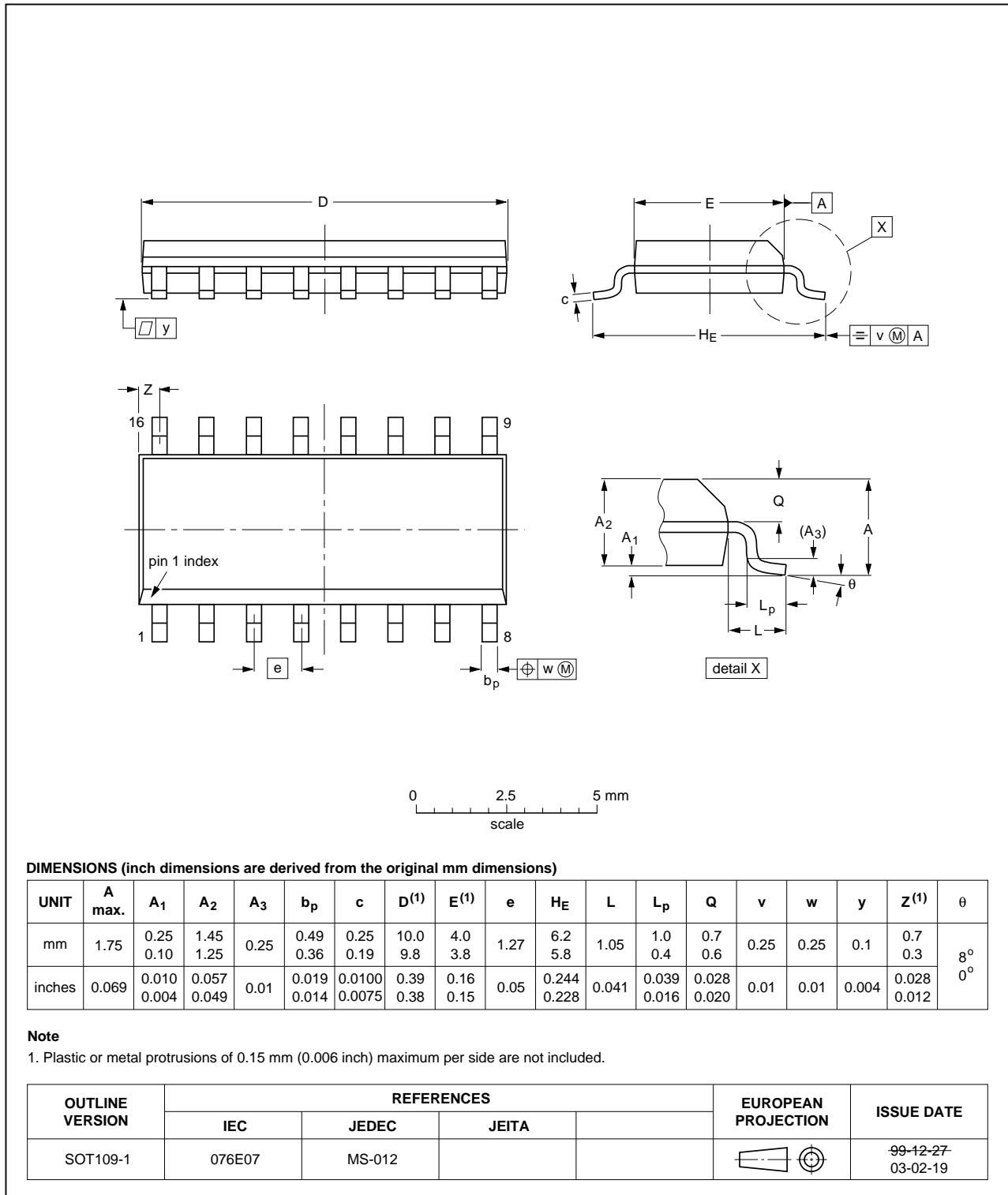


Fig 9. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

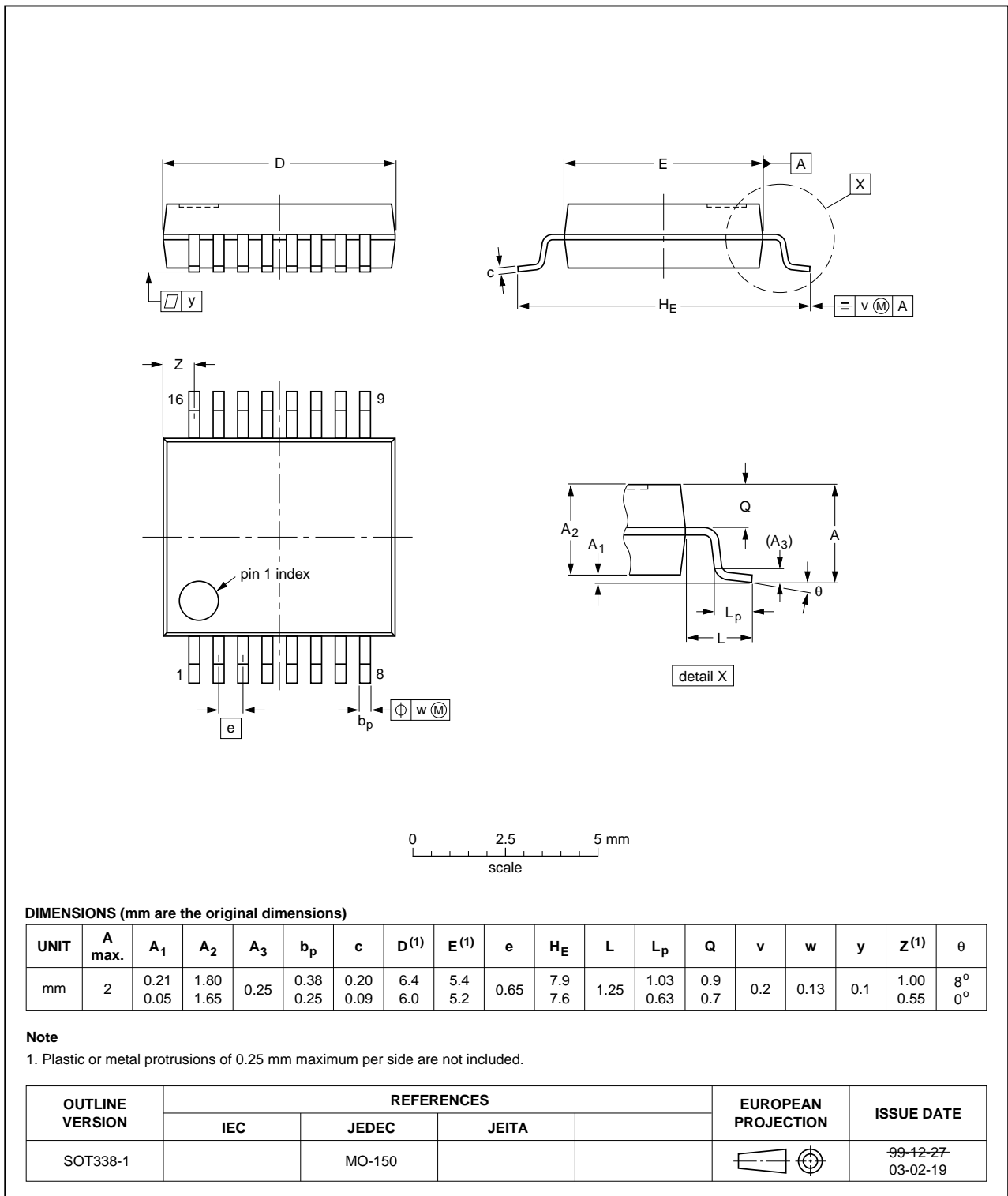


Fig 10. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

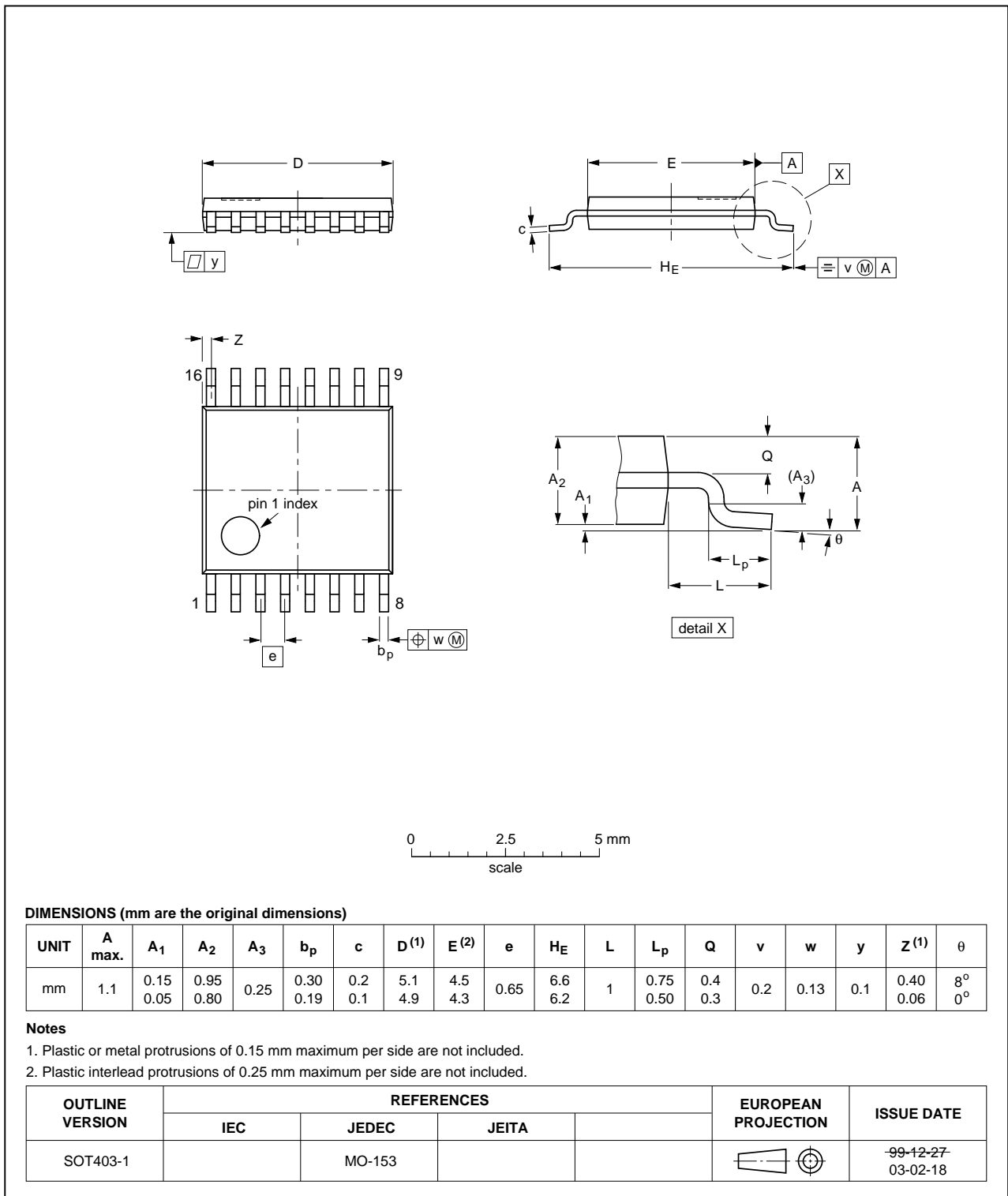


Fig 11. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

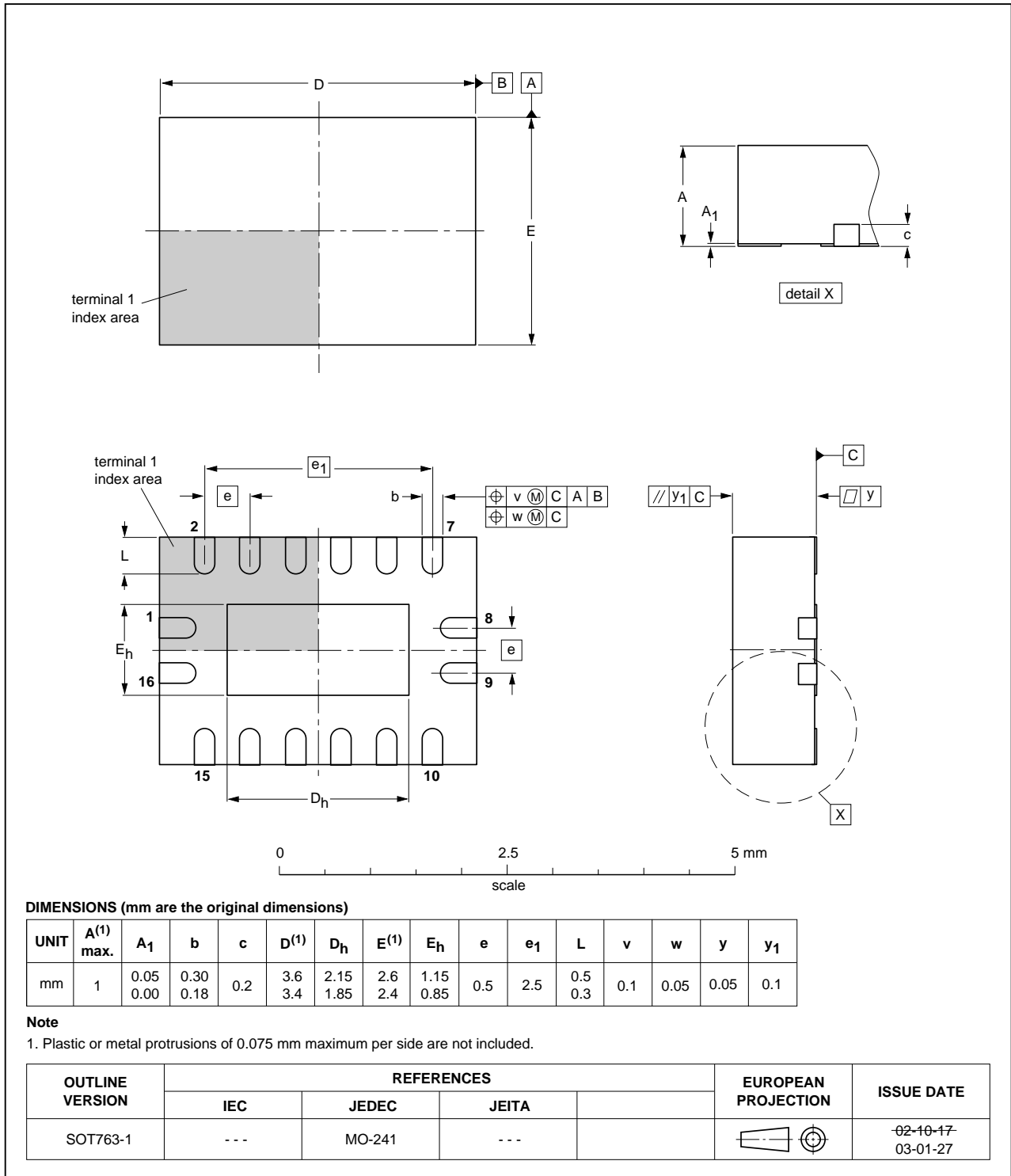


Fig 12. Package outline SOT763-1 (DHVQFN16)

## 13. Abbreviations

**Table 9. Abbreviations**

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC139 v.5	20111019	Product data sheet	-	74LVC139 v.4
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li><a href="#">Table 4</a>, <a href="#">Table 5</a>, <a href="#">Table 6</a>, <a href="#">Table 7</a> and <a href="#">Table 8</a>: values added for lower voltage ranges.</li> </ul>			
74LVC139 v.4	040315	Product specification	-	74LVC139 v.3
74LVC139 v.3	030519	Product specification	-	74LVC139 v.2
74LVC139 v.2	980428	Product specification	-	74LVC139 v.1
74LVC139 v.1	-	-	-	-





## 17. Contents

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